TMAG6180-Q1 汽车类高精度模拟 AMR 360° 角度传感器

1 特性

- 符合面向汽车应用的 AEC-Q100 标准：
  - 温度等级 0：-40°C 至 150°C
- 功能安全合规型
  - 专为功能安全应用开发
  - 有助于使 ISO 26262 系统设计满足 ASIL-B 要求的文档
- 高精度、低角度误差 AMR 传感器：
  - 0.1°（典型值）
  - 0.4°（在 3.3V 下、整个温度范围内的最大值）
  - 0.56°（在 5.5V 下、整个温度范围内的最大值）
- 高速 AMR 角度传感器：
  - < 2µs 的超低延迟支持高达 100krpm
- 具有低角度漂移，无需在整个温度范围内进行校准
- 正弦和余弦差分比例式模拟输出
- 支持差分端或单端应用
- 宽工作磁场范围：20mT 至 1T
- 快速启动时间：< 40µs
- 使用霍尔传感器的集成象限检测
  - 将 AMR 角度范围扩展至 360°
  - 可用于速度和方向
  - 开漏数字输出
- 电源电压范围：2.7V 至 5.5V

2 应用

- 电动助力转向
- 转向角传感器
- BLDC/PMSM 转子位置检测
- 电动自行车
- 雨刮器模块
- 传动器
- 伺服驱动器位置传感器
- 牵引电机

3 说明

TMAG6180-Q1 是一款基于各向异性磁阻 (AMR) 技术的高精度角度传感器。该器件集成信号调节放大器，并提供与所施加平面磁场的方向相关的差分正弦和余弦模拟输出。该器件还在 X 轴和 Y 轴上具有两个独立的霍尔传感器输出，可用于将传感器的角度范围扩展到 360°。

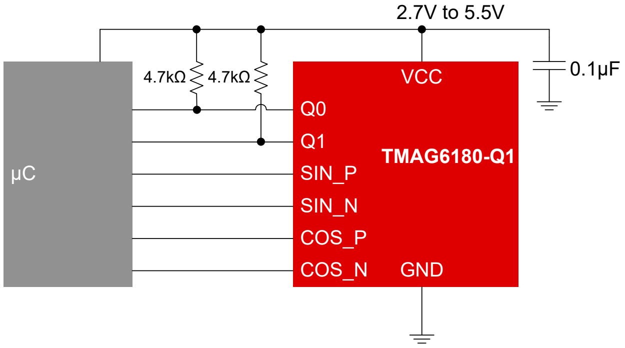
TMAG6180-Q1 具有宽工作磁场，可实现灵活的机械放置以及低延迟 (1.6µs) 输出，适用于转子位置检测等高速应用。该器件在正弦和余弦输出上具有超低延迟，可大大减少延迟相关角度误差，非常适合高达 100krpm 转子位置检测等高速应用。

TMAG6180-Q1 提供广泛的诊断功能，可满足严格的功能安全汽车和工业要求。该器件可在 －40°C 至 +150°C 的宽环境温度范围内保持稳定一致的性能，同时具有超小的热漂移和寿命误差。

封装信息

器件型号	封装(1)	封装尺寸(2)
TMAG6180-Q1	DGK（VSSOP，8）	3mm × 4.9mm

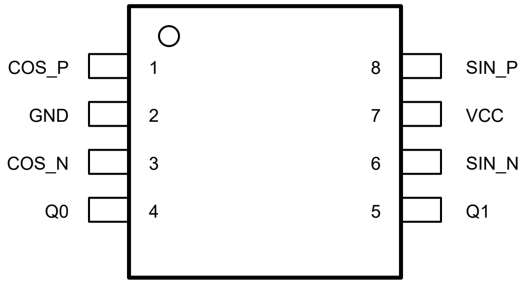
(1) 如需了解更多信息，请参阅节 10
(2) 封装尺寸（长 × 宽）为标称值，并包括引脚（如适用）。



应用方框图

Table of Contents

4 Pin Configuration and Functions



Not to scale

图 4-1. DGK Package 8-Pin VSSOP Top View

表 4-1. Pin Functions

PIN		TYPE[1]	DESCRIPTION
NO.	NAME		
1	COS_P	O	Differential cosine output (positive)
2	GND	G	Ground reference
3	COS_N	O	Differential cosine output (negative)
4	Q0	O	Quadrature 0 digital output (open drain)
5	Q1	O	Quadrature 1 digital output (open drain)
6	SIN_N	O	Differential sine output (negative)
7	VCC	P	Power supply
8	SIN_P	O	Differential sine output (positive)

(1) I = input, O = output, I/O = input and output, G = ground, P = power

5 Specifications

5.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)(1)

		MIN	MAX	UNIT
V_{CC}	Main supply voltage	–0.3	7	V
I_{OUT}	Output current (SIN_P, SIN_N, COS_P, COS_N, Q1, Q0)	–10	10	mA
V_{OUT}	Output voltage (SIN_P, SIN_N, COS_P, COS_N, Q1 ,Q0)	–0.3	7	V
T_J	Junction temperature	–40	170	°C
T_{stg}	Storage temperature	–65	150	°C

(1) Operation outside the Absolute Maximum Ratings may cause permanent device damage. Absolute maximum ratings do not imply functional operation of the device at these or any other conditions beyond those listed under Recommended Operating Conditions. If briefly operating outside the Recommended Operating Conditions but within the Absolute Maximum Ratings, the device may not sustain damage, but it may not be fully functional. Operating the device in this manner may affect device reliability, functionality, performance, and shorten the device lifetime.

5.2 ESD Ratings

				VALUE	UNIT
$V_{(ESD)}$	Electrostatic discharge	Human body model (HBM), per AEC Q100-002(1) HBM ESD classification level 2		±2000	V
		Charged device model (CDM), per AEC Q100-011 CDM ESD classification level C4B	All pins	±500	
			Corner pins (1, 4, 5, and 8)	±750	

(1) AEC Q100-002 indicates that HBM stressing shall be in accordance with the ANSI/ESDA/JEDEC JS-001 specification.

5.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

		MIN	NOM	MAX	UNIT
V_{CC}	Main supply voltage	2.7		5.5	V
T_A	Operating free air temperature	–40		150	C
C_L	Capacitive load on SIN_P, SIN_N, COS_P, COS_N	0.1		10	nF
I_L	Current load on SIN_P, SIN_N, COS_P, COS_N	–1		1	mA
B	Magnetic flux density for AMR saturation	20			mT

5.4 Thermal Information

THERMAL METRIC(1)		TMAG6180-Q1	UNIT
		DGK (VSSOP)	
		8 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance	166.8	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	57.8	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	88.7	°C/W
Ψ_{JT}	Junction-to-top characterization parameter	7.0	°C/W
Ψ_{JB}	Junction-to-board characterization parameter	87.1	°C/W

(1) For more information about traditional and new thermal metrics, see the Semiconductor and IC Package Thermal Metrics application report.

5.5 Electrical Characteristics

over operating free-air temperature range (unless otherwise noted); typical specifications are at T_A = 25°C

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
AMR Output Parameters						
V_{out}	Single-ended output voltage peak to peak	V_{CC} = 3.3V	57	62	67.5	%V_{CC}
V_{out}	Single-ended output voltage peak to peak	V_{CC} = 5.5V	55	60	65	%V_{CC}
k	Amplitude asynchronism ratio (Vpk Cos/ Vpk Vsin)	B = 30mT, V_{CC} = 3.3V	–2.3	0.3	2.3	%
		B = 30mT, V_{CC} = 5V	–2.4	0.3	2.4	%
V_{offset_room}	Differential offset of SIN/COS outputs at room	B = 30mT, T_A = 25°C, V_{CC} = 3.3V	–56		56	mV
		B = 30mT, T_A = 25°C, V_{CC} = 5V	–90		90	mV
V_{offset_tc}	Temperature coefficient of differential offset voltage	B = 30mT, V_{CC} = 3.3V		±0.1		mV/°C
		B = 30mT, V_{CC} = 5V		±0.1		mV/°C
V_{CM}	Common-mode output voltage	B = 30mT, V_{CC} = 3.3V	48	50	52	%VCC
		B = 30mT, V_{CC} = 5V	48	50	52	%VCC
V_{NOISE}	Output referred noise (differential)	B = 30mT, C_{load} = 100pF		0.5		mV_{rms}
R_{out}	Series output resistance			55		Ω
t_{agc_update}	Update rate of the automatic gain control	After V_{out} reaching 60% of V_{CC}		1		s
DC Power						
V_{CC_UV}	VCC undervoltage threshold			2.45	2.65	V
V_{CC_OV}	VCC overvoltage threshold			5.9	6.36	V
VCC_{RAMP}	Power supply ramp rate for proper device start-up	V_{CC} = 10% to 90% Specified by design			0.2	ms
I_{ACT}	Active mode current from VCC			6.5	10	mA
$t_{on\_startup}$	Power-on time during start-up	To achieve 90% of output voltages after VCC has reached final value (C_{LOAD} =100pF)		38	85	µs
Digital I/O						
V_{OL_Q}	Low level output voltage	I_O = 1mA on Q0, Q1 pins	0		0.4	V
Hall sensor outputs						
tpd	Propagation delay time per channel	Change in B_{OP} or B_{RP} to change in output		10		µs

5.6 Magnetic Characteristics

over operating free-air temperature range (unless otherwise noted); typical specifications are at T_A = 25°C

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
Angular Performance						
$ANG_{ERR\_DYN\_SE}$	Angular error linearity across temperature on continuous calibration (gain / offset) (single ended)	B = 30mT, V_{CC} = 3.3V, Magnetic field Rotation Speed = 1000rpm		0.1	0.35	deg
		B = 30mT, V_{CC} = 5V, Magnetic field Rotation Speed = 1000rpm		0.1	0.56	deg
$ANG_{ERR\_DYN\_DE}$	Angular error linearity across temperature on continuous calibration (gain / offset) (differential ended)	B = 30mT, V_{CC} = 3.3V, Magnetic field Rotation Speed = 1000rpm		0.1	0.4	deg
		B = 30mT, V_{CC} = 5V, Magnetic field Rotation Speed = 1000rpm		0.1	0.56	deg
$ANG_{ERR\_RTCAL\_SE}$	Angular error linearity across temperature after room temperature calibration (of offset / gain mismatch) (single ended)	B = 30mT, V_{CC} = 3.3V, Ideal magnet alignment		0.1	1.1	deg
		B = 30mT, V_{CC} = 5V, Ideal magnet alignment		0.1	1.1	deg
$ANG_{ERR\_RTCAL\_DE}$	Angular error linearity across temperature after room temperature calibration (of offset / gain mismatch) (differential ended)	B = 30mT, V_{CC} = 3.3V, Ideal magnet alignment		0.2	1.0	deg
		B = 30mT, V_{CC} = 5V, Ideal magnet alignment		0.1	0.95	deg
$ANG_{ERR\_NOCAL\_SE}$	Angular error linearity across temperature with no calibration of gain / offset (single ended)	B = 30mT, V_{CC} = 3.3V, Ideal magnet alignment		0.5	1.52	deg
		B = 30mT, V_{CC} = 5V, Ideal magnet alignment		0.5	1.26	deg
$ANG_{ERR\_NOCAL\_DE}$	Angular error linearity across temperature with no calibration of gain / offset (differential ended)	B = 30mT, V_{CC} = 3.3V, Ideal magnet alignment		0.4	1.1	deg
		B = 30mT, V_{CC} = 5V, Ideal magnet alignment		0.4	1.0	deg
ANG_{LT_DRIFT}	Angle error lifetime drift	B = 30mT		0.05	±0.75	deg
ANG_{HYST}	Angle hysteresis error	B = 30mT		0.01	0.06	deg
ANG_{OE_ERR}	Orthogonality error	B = 30mT		0.01	0.051	deg
ANG_{NOISE}	Angular RMS (1-sigma) noise in degrees	B = 30mT, C_{load} = 100pF		0.01	0.06	deg
t_{del_amr}	Propagation Delay time	C_{load} = 100pF		1.6		μs
BW_{3dB_amr}	3dB Bandwidth	C_{load} = 100pF		100		KHz
ϕ_{err}	Phase error	Magnetic Field Rotation Speed = 10000rpm, C_{load} = 100pF		0.15		deg
Hall sensor characteristics						
$B_{OP(X)}$,$B_{OP(Y)}$	Magnetic field operating point			3		mT
$B_{RP(X)}$,$B_{RP(Y)}$	Magnetic field release point			–3		mT
B_{OP} - B_{RP}	Magnetic hysteresis		3.5	6		mT
B_{SYM_OP}	Operating point symmetry	Bop(x) – Bop(y)		±0.5		mT
B_{SYM_RP}	Release point symmetry	Brp(x) – Brp(y)		±0.5		mT
B_{SYM_RP}	Release point symmetry	Brp(x) – Brp(y)		0		mT
t_{PD_HALL}	Propagation delay time per channel	Change in B_{OP} or B_{RP} to change in output		10		μs

5.7 Typical Characteristics

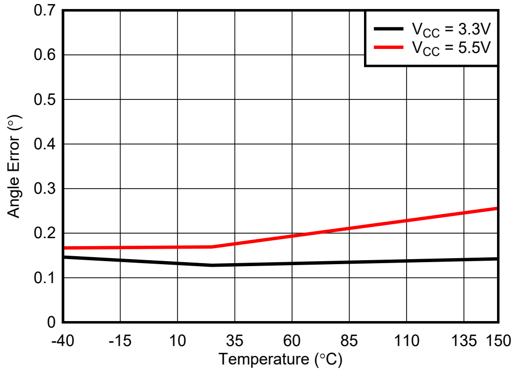


图 5-1. Absolute Angle Error. Differential with Dynamic Calibration

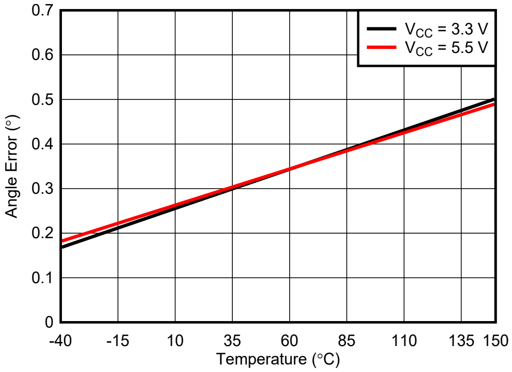


图 5-2. Absolute Angle Error. Differential with Room Temperature Calibration

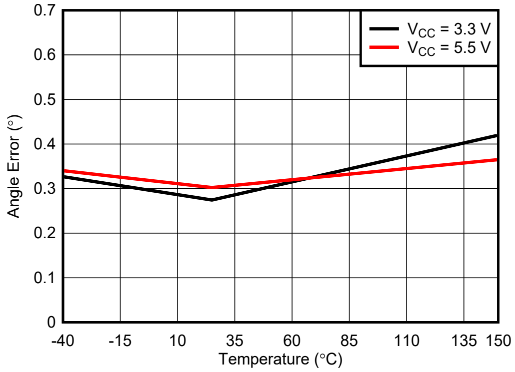


图 5-3. Absolute Angle Error. Differential with No Calibration

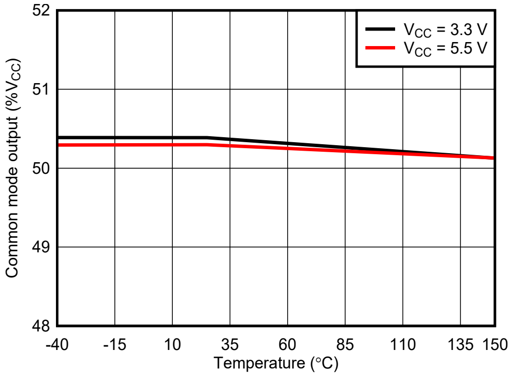


图 5-4. AMR Common-Mode Output Voltage

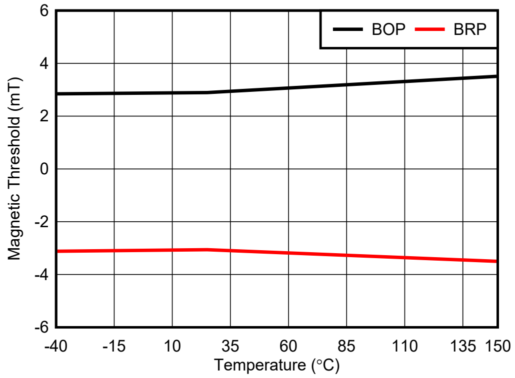


图 5-5. Hall Sensor BOP and BRP Typical Threshold

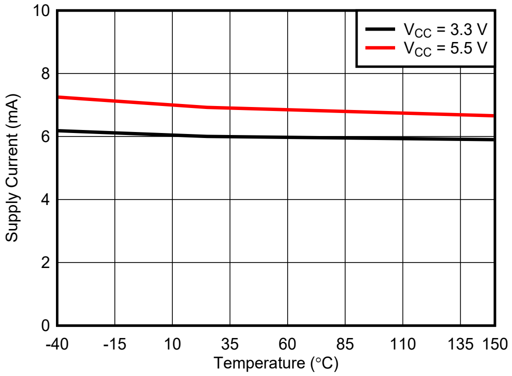


图 5-6. Active Mode Current

6 Detailed Description

6.1 Overview

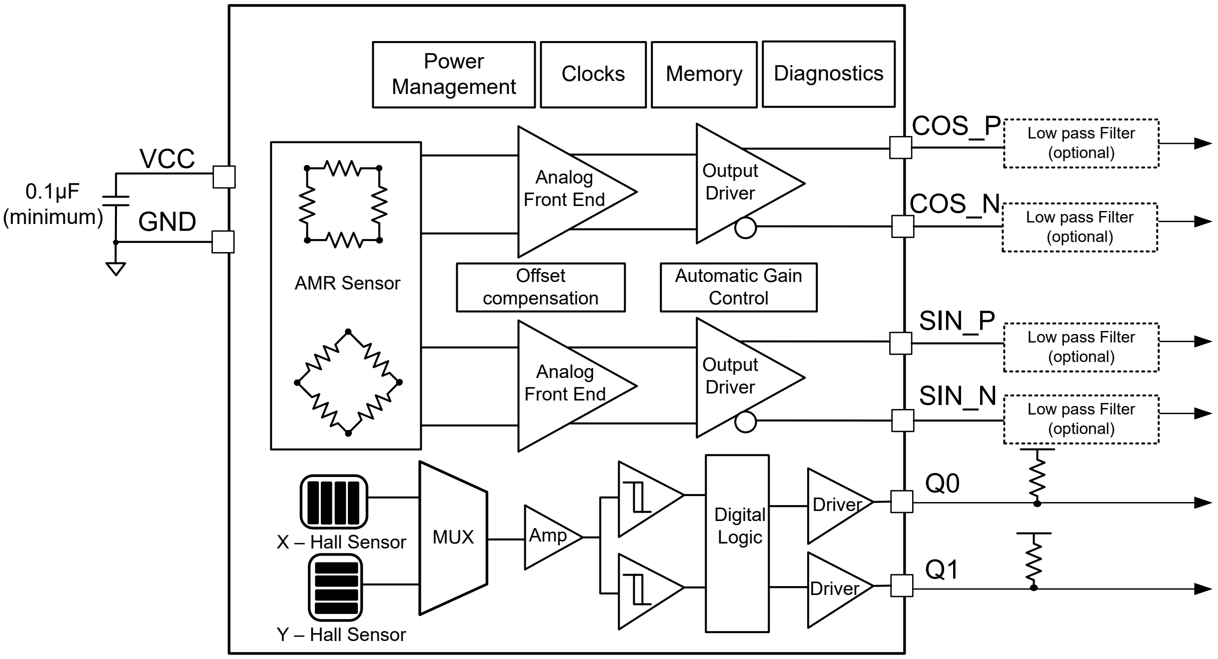
The TMAG6180-Q1 is a high-precision angle sensor based on the AMR sensor technology vertically integrated on top of the integrated amplifiers on silicon. The differential output sine and cosine signals from the AMR sensor are proportional to the angle of the applied magnetic field. The sine and cosine signals are internally signal conditioned, temperature compensated, and driven by differential output amplifiers with the ability to drive large capacitive loads. The output voltages of the AMR sensor are ratiometric to the supply voltage, therefore the external ADC can use the supply voltage as a reference.

TMAG6180-Q1 integrates X and Y Hall sensors to provide quadrature outputs on pins Q0 and Q1, respectively. The Hall effect sensors are chopper stabilized, signal conditioned, and multiplexed to provide two digital latched outputs. These outputs can be used to extend the angle sensing range of the AMR sensor from 180 degrees to 360 degrees.

The TMAG6180-Q1 contains the following functional and building blocks:

- The Power Management and Oscillators block contains internal regulators, biasing circuitry, a low-frequency, wake-up oscillator and a high-frequency, wake-up oscillator, overvoltage detection circuitry, and undervoltage detection circuitry
- The AMR sensor contains two Wheatstone bridges made of magnetic resistive sensors, each sensing one of the components of the applied magnetic field, the sine and the cosine components.
- The AMR sensing path contains the signal conditioning amplifiers, offset compensation, automatic gain control circuitry and the output drivers.
- The Quadrature Detection Path contains the X and Y Hall sensors, related biasing circuitry, signal conditioning, logic comparators and digital logic to drive the Q1 and Q0 outputs
- The Internal memory block supports the factory-programmed values
- The diagnostic blocks support background diagnostic checks of the internal circuitry

6.2 Functional Block Diagram



6.3 Feature Description

6.3.1 Magnetic Flux Direction

The TMAG6180-Q1 is sensitive to the magnetic field component in X and Y directions. The X and Y fields are in-plane with the package. The device generates sine and cosine outputs from the AMR based on the reference position (0°). See Direction of Sensitivity.

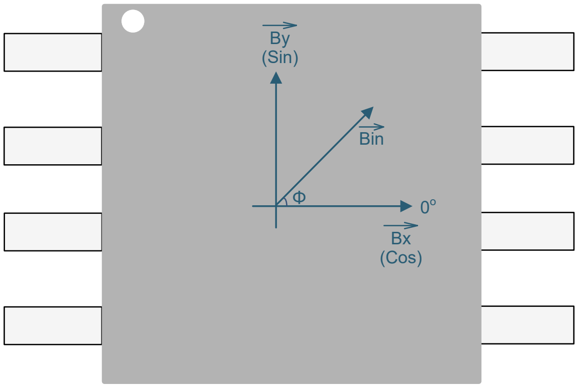


图 6-1. Direction of Sensitivity

6.3.2 Sensors Location and Placement Tolerances

Location of AMR Sensor and Hall Elements shows the location of the AMR sensor and X, Y Hall elements, along with the placement tolerances inside the TMAG6180-Q1.

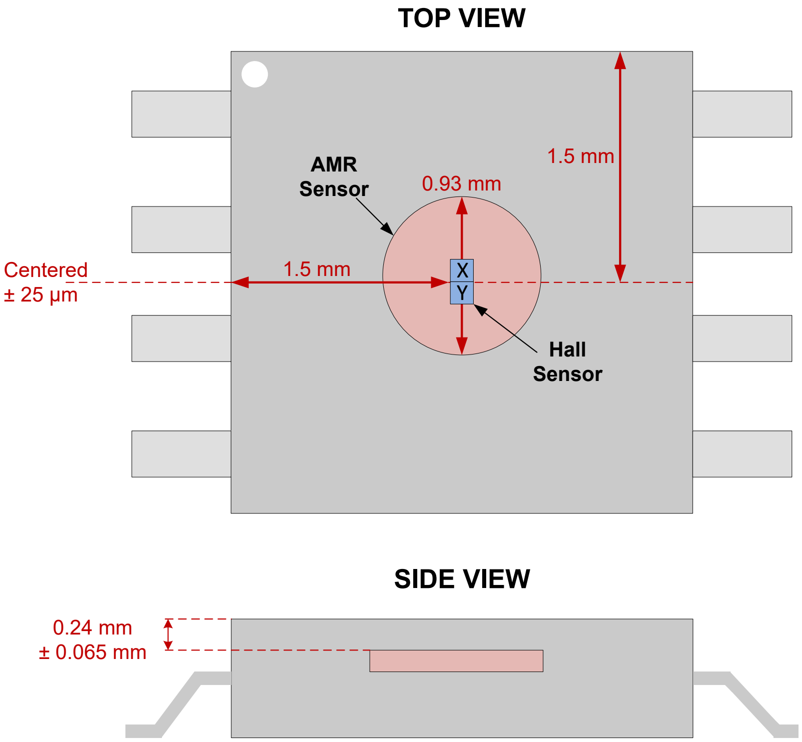


图 6-2. Location of AMR Sensor and Hall Elements

The center of the AMR and Hall sensors lie in the center of the package. Die Rotation Tolerances in the Package shows the tolerances of the die rotation within the package. This causes a reference angle error (Φ) of ± 3°.

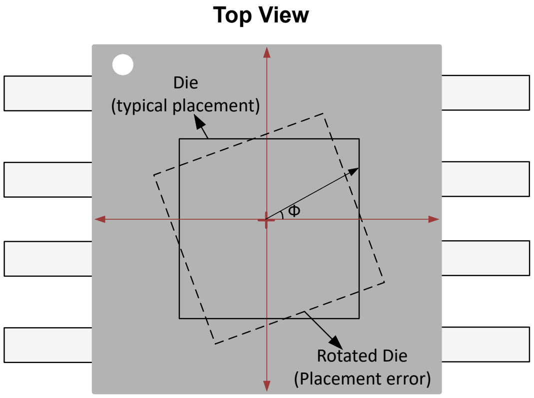


图 6-3. Die Rotation Tolerances in the Package

6.3.3 Magnetic Response

The AMR sensor has two components that are sensitive to the in-plane magnetic field X and Y axes parallel to the chip surface. 节 6.3.3 shows the AMR sensor with the differential sine and cosine outputs SIN_P, SIN_N, COS_P and COS_N. The outputs have an electrical range of 180 degrees. If the mechanical angle between the sensor reference and the direction of the magnetic field is θ, then the AMR outputs correspond to cosine 2θ and sine 2θ respectively. For every 360° rotation of the external magnetic field, the AMR outputs provide two periods, at 180° sensing range for each period. Hence, for a dipole magnet rotating at speed of *f*, the electrical output from the AMR sensor outputs can be at twice the frequency at *2f*. Use 方程式 1 to calculate the angle of the magnetic field is calculated using an arctangent2 function.

$$\theta = \frac{\mathrm{arctan2}\left(\frac{\mathrm{Vsin}}{\mathrm{Vcos}}\right)}{2} \tag{1}$$

where

- Vsin is the differential sine output
- Vcos is the differential cosine output

The AMR sensor is sensitive only to the direction of the magnetic field and has a wide operating magnetic field range. The voltage levels of the AMR outputs are independent of the absolute flux density as long as the magnetic flux density is above the minimum recommended operating fields.

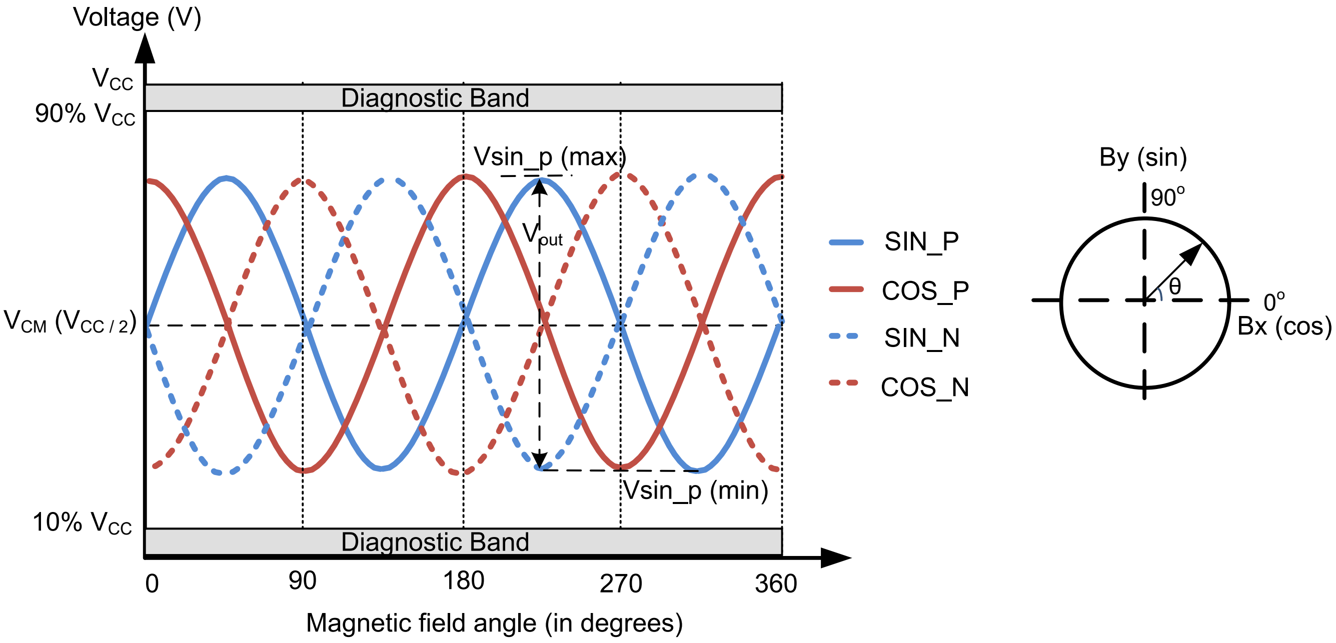


图 **6-4. AMR Sensor Outputs Magnetic Response**

The two integrated Hall sensors X and Y that are sensitive to the in-plane X and Y axes similar to the AMR sensor. 图 6-5 shows both the Hall outputs reacting to the input field by going low when the field is higher than operating point (B_{OP}) and going high when the field is lower than returning point (B_{RP}).

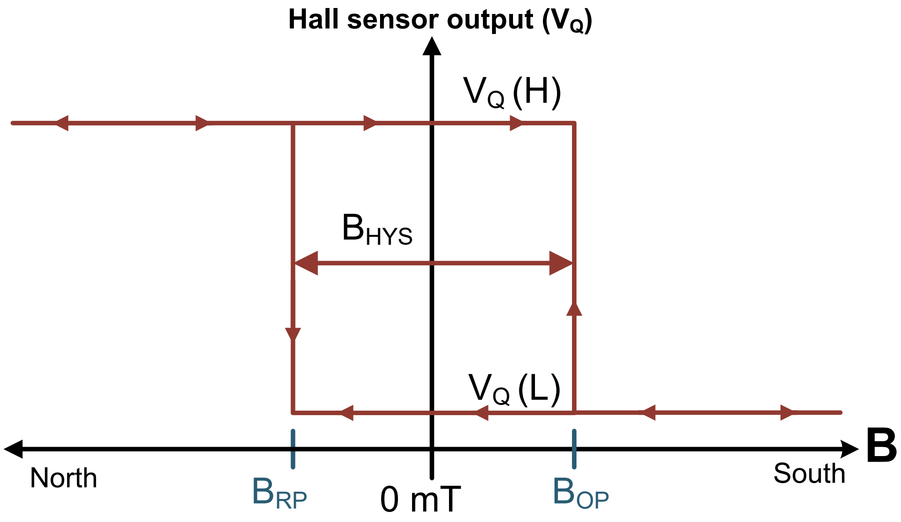
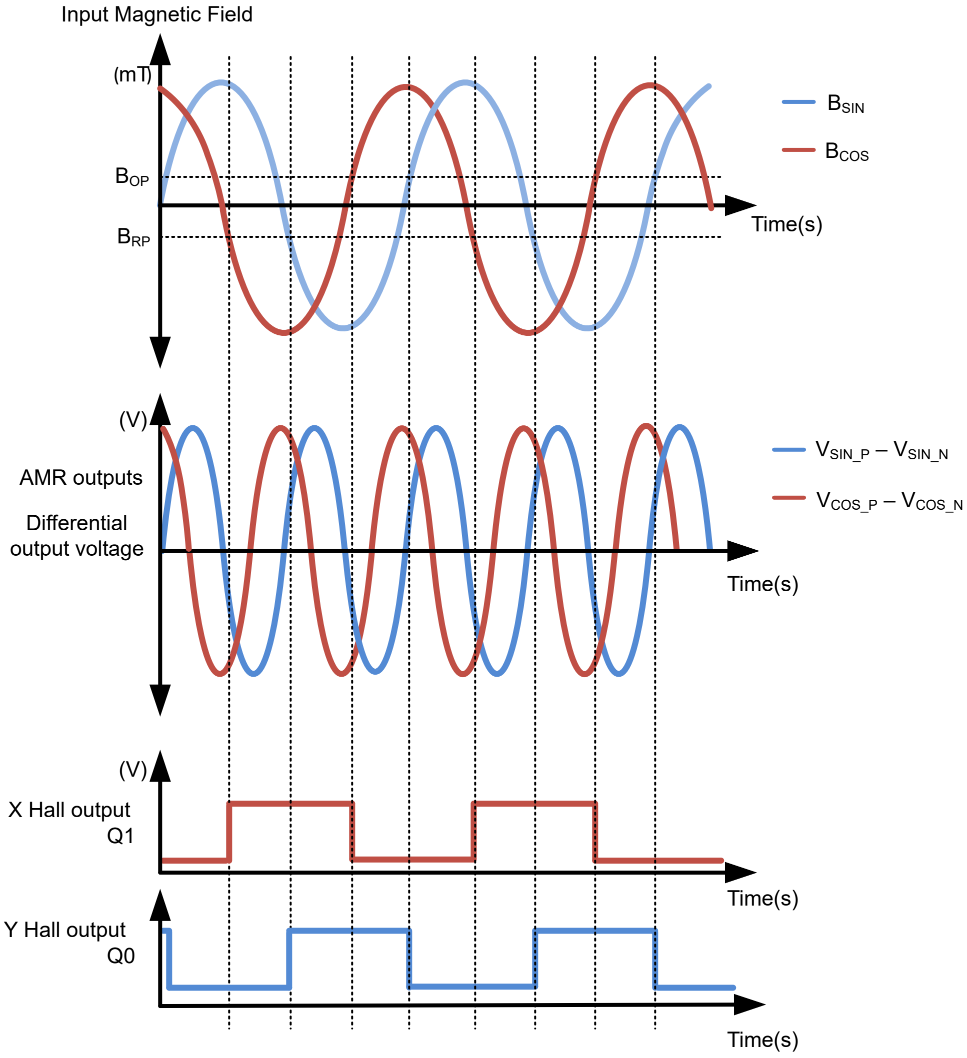


图 6-5. Hall Sensor Magnetic Response

For a rotating input magnetic field, with the X and Y components of B_{SIN} and B_{COS} respectively, 图 6-6 shows the response of the AMR and Hall sensors. The integrated X and Y Hall sensors provide digital outputs (Q0 and Q1, respectively). See the *Functional Block Diagram*. The Hall sensors have a 360° compared to the 180° angle range of the AMR sensors. By utilizing the digital outputs of the Hall sensors, the angle range of the AMR sensor can be extended to 360°.

图 6-6. Magnetic Response of AMR and Hall sensors



6.3.4 Parameters Definition

6.3.4.1 AMR Output Parameters

The single-ended output signals SIN_P, SIN_N, COS_P and COS_N are shown in 图 6-4. These signals are ratiometric to the supply voltage (V_{CC}). The common-mode voltage (V_{CM}) of the individual signals is half of the supply voltage (V_{CC} /2). For single-ended signals, V_{OUT} is defined as the difference between the maximum and minimum output voltage for a rotating magnetic field. Use 方程式 2 to calculate $V_{OUT\_SIN\_P}$.

$$V_{OUT\_SIN\_P} = V_{SIN\_P(max)} - V_{SIN\_P(min)} \tag{2}$$

where

- $V_{SIN\_P\ (min)}$ is the minimum output voltage across the full magnetic angle range
- $V_{SIN\_P\ (max)}$ is the maximum output voltage across the full magnetic angle range

Typically, V_{OUT} is around 60% of the supply voltage (V_{CC}). The diagnostic band shown in AMR Sensor Outputs Magnetic Response indicates that the output signals are outside normal operating range and indicates a presence of fault.

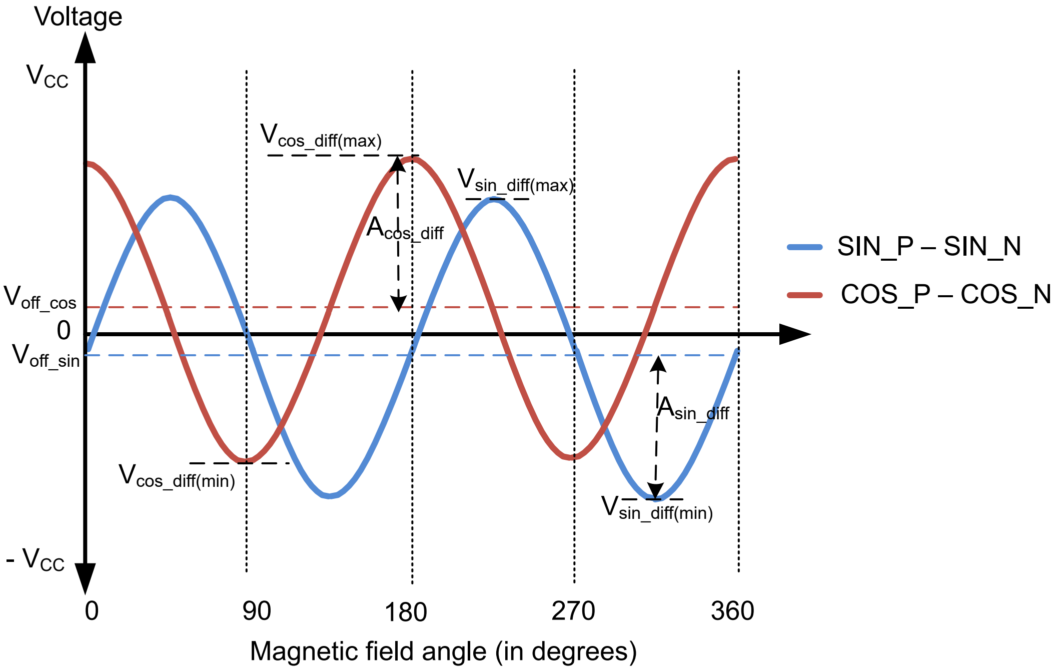


图 6-7. AMR Differential Ended Output Signals

The differential sine and cosine output signals shown in 图 6-7 are generated from the corresponding sine and cosine single-ended outputs. Use 方程式 3 and 方程式 4 to calculate the differential voltages.

$$V_{sin\_diff} = V_{SIN\_P} - V_{SIN\_N} \tag{3}$$

$$V_{cos\_diff} = V_{COS\_P} - V_{COS\_N} \tag{4}$$

The offset of the differential signals is the average of the maximum and minimum voltages of the sine or cosine signals. Use 方程式 5 and 方程式 6 to calculate the offsets for the sine and cosine signals.

$$V_{offset\_sin} = \frac{V_{sin\_diff(max)} + V_{sin\_diff(min)}}{2} \tag{5}$$

$$V_{offset\_cos} = \frac{V_{cos\_diff(max)} + V_{cos\_diff(min)}}{2} \tag{6}$$

For single-ended signals, the offset is the common-mode voltage (V_{CM}).

Use 方程式 7 to calculate the differential offset for sine and cosine channels at any given temperature, T_A.

$$V_{offset} = V_{offset,\ room} \times \left(1 + V_{offset\_TC} \times \left(T_A - 25^oC\right)\right) \tag{7}$$

where

- V_{Offset_TC} is the temperature drift coefficient of the offset
- V_{Offset_room} is the room temperature offset

Use 方程式 8 and 方程式 9 to calculate the amplitudes of the differential signals.

$$A_{sin\_diff} = \frac{V_{sin\_diff(max)} - V_{sin\_diff(min)}}{2} \tag{8}$$

$$A_{cos\_diff} = \frac{V_{cos\_diff(max)} - V_{cos\_diff(min)}}{2} \tag{9}$$

Use 方程式 10 to calculate the amplitude for single-ended signals.

$$A_{sin\_p} = \frac{V_{sin\_p(max)} - V_{sin\_p(min)}}{2} \tag{10}$$

Amplitude asynchronism refers to the amplitude mismatch error between sine and cosine channels. Use 方程式 11 to calculate the amplitude mismatch error.

$$k = 1 - \left(\frac{A_{cos\_diff}}{A_{sin\_diff}}\right) \tag{11}$$

The sine and cosine output signals are typically out-of-phase by 90 degrees. However, the sine and cosine outputs from the sensor can be different than the ideal 90 degrees if an internal phase error occurs owing to sensor and other on chip circuitry non-idealities. This error is referred to as the orthogonality error. This error is defined as the angle error between the zero crossing of the cosine output and maximum value of the sine outputs.

The hysteresis error (ANG_{hyst}) refers to the largest angle error difference between a clockwise rotation and a counter-clockwise rotation.

For the AMR sensor, the orthogonality error and the hysteresis errors are negligible.

6.3.4.2 Transient Parameters

Propagation delay (t_{del_amr}) is defined as the time taken for signal to propagate from magnetic input change to the sine and cosine AMR outputs. The bandwidth limitation of the internal signal conditioning amplifiers causes a phase shift on the applied magnetic field. The propagation delay increases based on the speed of the rotating field and is specified at the maximum speed of the recommended magnetic field. 图 6-8shows an input rotating magnetic field and the response of the AMR outputs. The propagation delay in the signal path leads to a phase error.

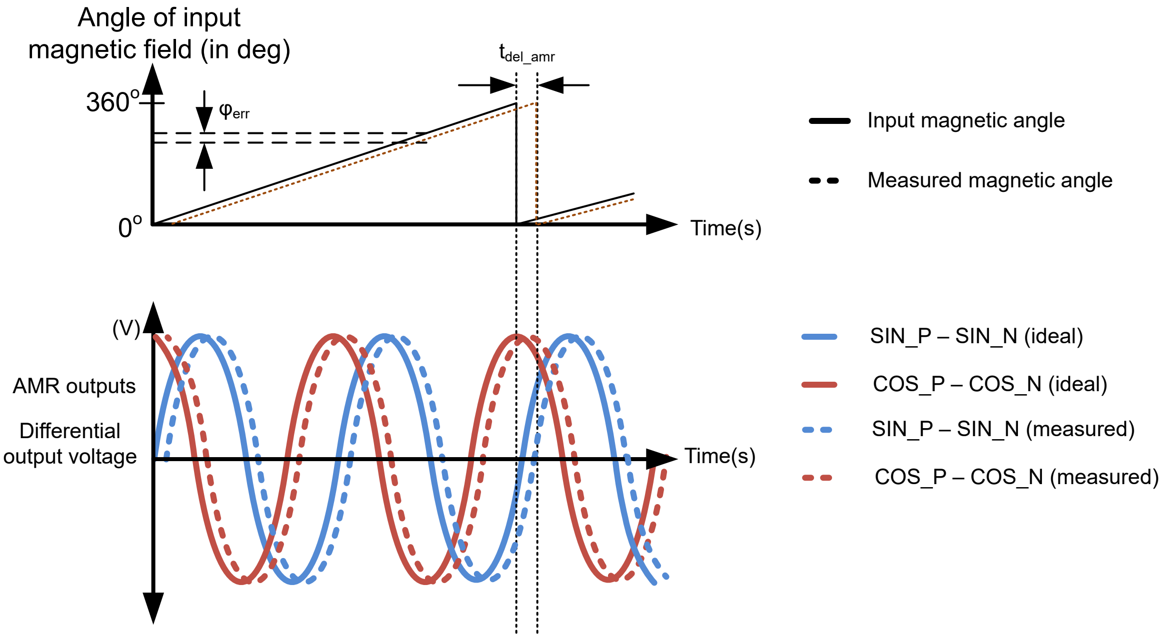


图 6-8. AMR Output Propagation Delay and Phase Error

The phase error (ϕ_{err}) refers to the angle error between the input magnetic field and output of the sensor. This error increases with the speed of the rotating magnetic field and the propagation delay of the AMR sensor. Typically, this error can be compensated to the first order if the speed of the rotating magnetic field is known.

6.3.4.2.1 Power-On Time

The power-on time during start-up ($T_{on\_startup}$) is defined as the time it takes for the AMR outputs to reach to 90% of their final value (under a constant magnetic field) after the V_{CC} reaches $V_{CC(min)}$. 图 6-9 shows the power-on time of the device during a V_{CC} ramp.

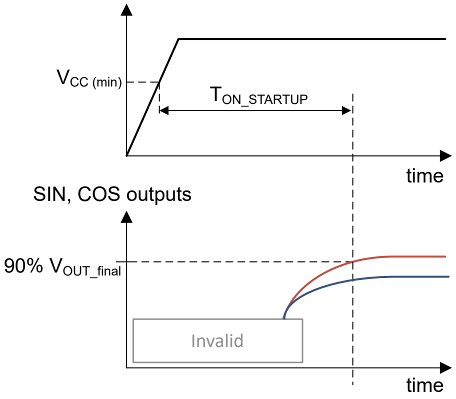


图 6-9. Power-On Time During Start-Up

6.3.4.3 Angle Accuracy Parameters

The overall angle error represents the relative angular error. 节 6.3.4.3 shows the deviation from the reference line after zero angle definition..

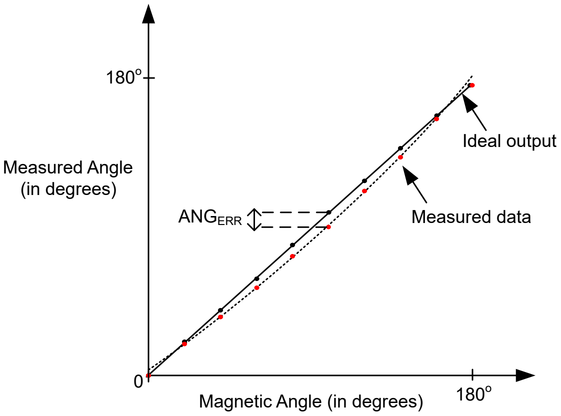


图 6-10. Angle Error

The uncalibrated angular error ($ANG_{ERR\_NOCAL\_DE}$) is defined as the maximum deviation from an ideal angle without any offset and amplitude mismatch calibration for the VSIN and VCOS differential signals. For single-ended signals, the uncalibrated angular error is denoted by $ANG_{ERR\_NOCAL\_SE}$.

The single point calibration angular error ($ANG_{ERR\_RTCAL\_DE}$) is defined as the maximum deviation from an ideal angle after the offset calibration is applied to the VSIN and VCOS differential signals at room temperature (25°C). For single-ended signals, the room-temperature calibrated angular error is denoted by $ANG_{ERR\_RTCAL\_SE}$.

The dynamic angular error (ANG_{ERR_DYN}) is defined as the maximum deviation from an ideal angle with the continuous offset and gain calibration applied to the VSIN and VCOS differential signals. The error is measured at 1krpm and includes the phase error owing to the propagation delay of the AMR outputs.

6.3.4.4 Hall Sensor Parameters

The Hall sensors X and Y have factory-calibrated operating (B_{OP}) and release points (B_{RP}). The operating and release points shown in 图 6-4 give the magnetic hysteresis for each Hall sensor.

Use 方程式 12 and 方程式 13 to calculate the symmetry point for each axis.

$$B_{SYM(X)} = B_{OP(X)} + B_{RP(X)} \tag{12}$$

where

- $B_{OP\ (X)}$ and $B_{RP\ (X)}$ represent the operating and release points for X Hall sensor

$$B_{SYM(Y)} = B_{OP(Y)} + B_{RP(Y)} \tag{13}$$

where

- $B_{OP\ (Y)}$ and $B_{RP\ (Y)}$ represent the operating and release points for Y Hall sensor

Use 方程式 14 to calculate the operating point symmetry.

$$B_{SYM\_OP} = B_{OP(X)} - B_{OP(Y)} \tag{14}$$

Use 方程式 15 to calculate the release point symmetry.

$$B_{SYM\_RP} = B_{RP(X)} - B_{RP(Y)} \tag{15}$$

6.3.5 Automatic Gain Control (AGC)

The TMAG6180-Q1 features an automatic gain control circuitry to reduce the drift of the AMR sensor outputs across temperature. The device changes the gain of the output drivers to keep the final output within an appropriate voltage range on SIN_P, SIN_N, COS_P and COS_N. The AGC block uses the square root of the sum of the squared amplitudes of the two channels to sense amplitude of output signals and set gain selection. The AGC block sets the gain for sine and cosine channels, meaning that the peak-to-peak amplitude of single-ended voltages, V_{OUT} is within the range listed in *Specifications*. The AGC block changes the gain of both the sine and cosine channels simultaneously.

If the outputs are out of the normal operating range, the AGC block changes the gain of the sine and cosine channels by a step size of ±1% V_{CC} at an interval of t_{agc_update}, typically around 1 second, as defined in *Specifications*. 图 6-11 shows the differential AMR outputs for a continuously rotating input field. The shaded area represents the *No AGC Control* band that represents ±5% of V_{CC} and is centered at 60% of V_{CC}. Notice that the AGC loop reduces the gain and updates the amplitude at a step size of 1% V_{CC} as the sine and cosine signals drift outside of the shaded region. If the outputs remain within the shaded region, then no action is taken by the AGC control loop.

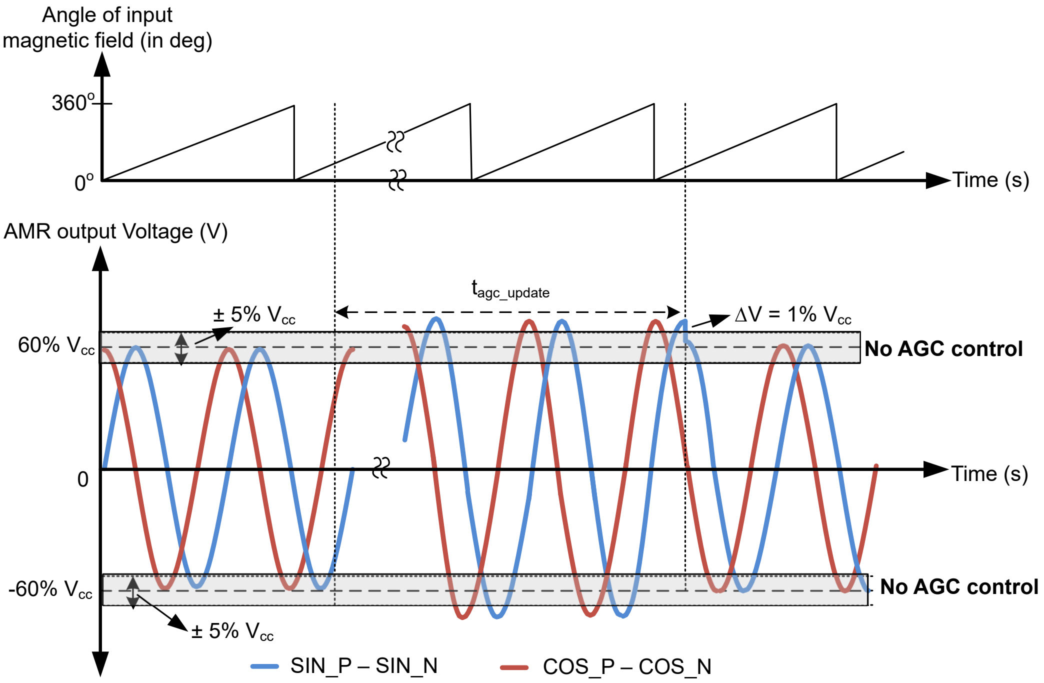


图 6-11. Timing Diagram Showing the Operation of Automatic Gain Control

6.3.6 Safety and Diagnostics

The TMAG6180-Q1 supports several device and system level diagnostics features to detect, monitor, and report failures during the device operation.

In the event of a failure, the TMAG6180-Q1 is placed in a FAULT state, where the outputs from the AMR sensors are placed in a high-impedance state. As shown in the *Application and Implementation* section, users can add pullup or pulldown resistors on SIN_P, SIN_N, COS_P, COS_N pins at the termination site (that is the microcontroller). The resistors are generally pulled up to supply voltage or pulled down to ground such that the ADC code on MCU is out of expected range. This state signal faults to the microcontroller.

In the fault state, the digital outputs Q0 and Q1 are not driven internally by the device.

The TMAG6180-Q1 performs the following device and system level checks:

6.3.6.1 Device Level Checks

- AMR signal path checks
  - AMR sensor bias check
  - AMR output signals common-mode check
  - Automatic gain control loop check
- Hall sensor signal path checks
  - Hall sensor bias and resistance check
  - Hall sensor comparator check
- Power management and supporting circuitry checks
  - Internal LDO undervoltage check
  - Internal clocks integrity check
- Internal memory integrity check (or a cyclic redundancy check – CRC)

6.3.6.2 System Level Checks

- V_{CC} undervoltage and overvoltage check
- Pin level opens and short checks

6.4 Device Functional Modes

6.4.1 Operating Modes

The TMAG6180-Q1 has primarily one mode of operation when all the conditions in the *Recommended Operating Conditions* are met. When the part detects an internal fault, the device switches into a fault mode (safe state). 图 6-12 shows the state transition for TMAG6180-Q1.

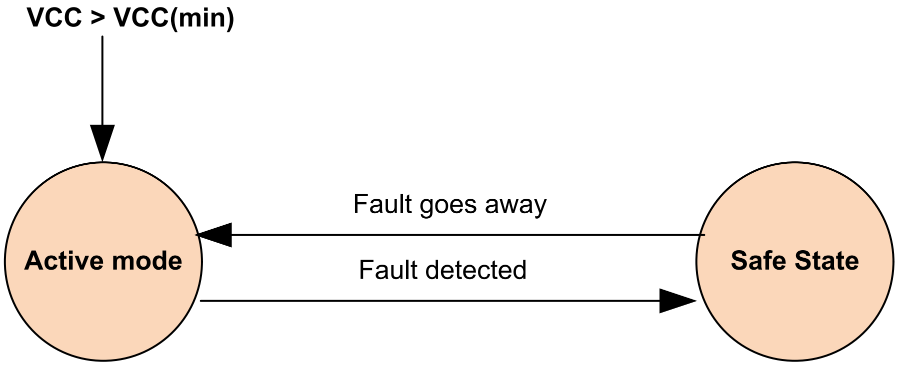


图 **6-12. TMAG6180-Q1 State Transition Diagram**

6.4.1.1 Active Mode

The device starts powering up after the V_{CC} supply crosses the minimum threshold as specified in the *Recommended Operating Conditions* table. The TMAG6180-Q1 enters the active mode, in which the SIN_P, SIN_N, COS_P and COS_N outputs actively provide the angle of the applied magnetic field. The average current consumption during the active conversion is I_{ACT}.

6.4.1.2 Fault Mode

The TMAG6180-Q1 supports extensive fault diagnostics as detailed in the *Diagnostics* section. When a fault is detected, the part enters the fault mode. In this mode, the AMR outputs and the Q0 and Q1 Hall outputs are placed in a high-impedance state.

7 Application and Implementation

备注

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI’ s customers are responsible for determining suitability of components for their purposes, as well as validating and testing their design implementation to confirm system functionality.

7.1 Application Information

7.1.1 Power Supply as the Reference for External ADC

The AMR output signals of the TMAG6180-Q1 are ratiometric to the supply voltage, V_{CC}. This enables the external ADC to use the TMAG6180-Q1 supply voltage as a reference and eliminate the errors which can arise if a separate reference voltage is used. This also enables the optimization of the external ADC input range. TI therefore recommends to use the supply voltage (V_{CC}) as the reference for the external ADCs. TI also recommends using a 0.1µF bypass capacitor to minimize the noise on the power supply.

7.1.2 AMR Output Dependence on Airgap Distance

The AMR sensor is only sensitive to the direction of the applied magnetic field along the X-Y plane parallel to the chip surface. The applied magnetic field from a rotating magnet can vary based on the airgap distance between the TMAG6180-Q1 and the magnet.

As long the absolute magnetic field is above the minimum field listed in *Recommended Operating Conditions*, the angle accuracy from the AMR outputs are independent of the value of the applied magnetic field.

7.1.3 Calibration of Sensor Errors

The TMAG6180-Q1 is factory-calibrated for best angular accuracy. Some of the electrical errors from the sensor that impact the angle accuracy can be calibrated out for achieving the best performance. 图 7-1 shows the impact of the different sensor error parameters such as offset, amplitude mismatch and orthogonality error on the angle accuracy.

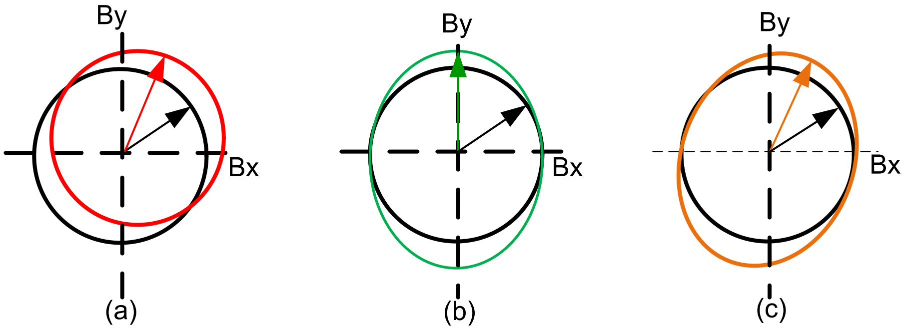


图 7-1. Angle Accuracy Impact Owing to Sensor Electrical Errors (a) Offset Error (b) Amplitude Mismatch Error (c) Orthogonality Error

Based on the parameters defined in *AMR Output Parameters*, use 方程式 16 to calculate the angle from the AMR sensors.

$$\theta = \frac{\operatorname{arctan2}\left(\frac{A_{\sin}\sin(2\theta) + V_{\mathrm{offset\_sin}}}{A_{\cos}\cos(2\theta) + V_{\mathrm{offset\_cos}}}\right)}{2} \tag{16}$$

where

- $V_{\mathrm{offset\_sin}}$ and $V_{\mathrm{offset\_cos}}$ are the differential offsets of the sine and cosine outputs
- $A_{\sin}$ and $A_{\cos}$ are the differential amplitude of the sine and cosine outputs

The impact of the angle accuracy owing to the orthogonality error and the hysteresis errors is negligible for the TMAG6180-Q1 and can be ignored.

To calibrate the offset and amplitude mismatch errors, the magnetic field rotates over the entire range and the sine and cosine outputs are sampled continuously to obtain the minimum and maximum values of the outputs.

Users can calculate the average of the minimum and maximum values of the respective outputs across the full angle range to find the offset error of the sine and cosine outputs. Use 方程式 17 and 方程式 18 to calculate the offset correction parameters for sine and cosine.

$$V_{\mathrm{os\_sin\_cal}} = \frac{V_{\sin(\max)} + V_{\sin(\min)}}{2} \tag{17}$$

$$V_{\mathrm{os\_cos\_cal}} = \frac{V_{\cos(\max)} + V_{\cos(\min)}}{2} \tag{18}$$

Users can calculate the difference of the minimum and maximum values of the respective outputs across the full angle range to find the amplitude of the sine and cosine outputs. Use 方程式 19 to calculate the amplitude correction parameters for sine and cosine.

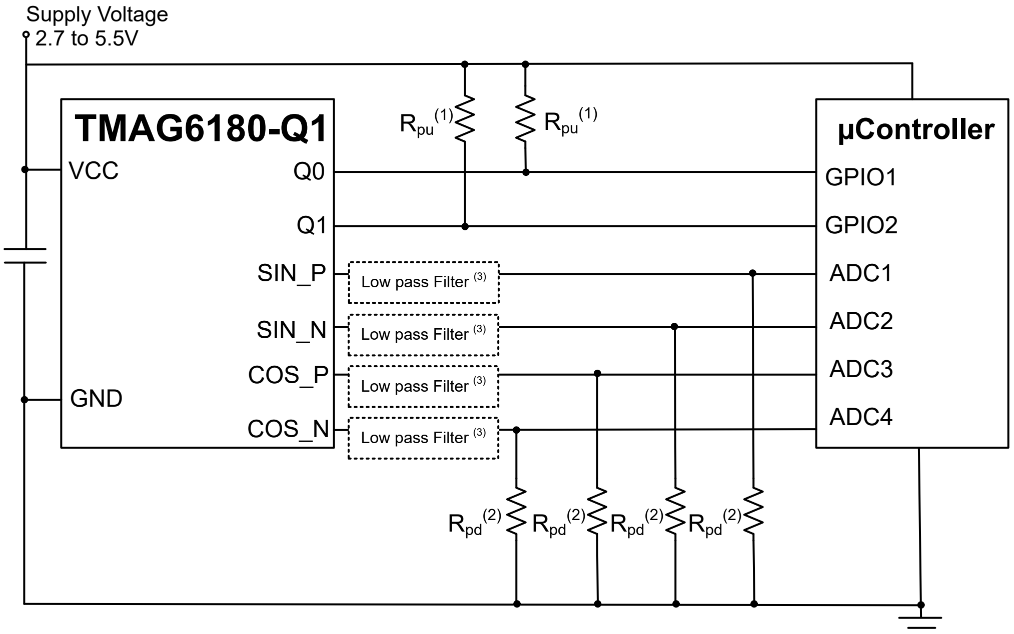
$$A_{\mathrm{corr}} = 1 - \frac{V_{\sin(\max)} - V_{\sin(\min)}}{V_{\cos(\max)} - V_{\cos(\min)}} \tag{19}$$

7.2 Typical Application

The TMAG6180-Q1 AMR angle sensor can be used either in single-ended output mode or differential output mode. The TMAG6180-Q1 has the drive capability to either drive differential or single-ended SAR or Sigma Delta ADCs. Typically, an external microcontroller processes the AMR output signals to extract the angular position.

The differential-ended output mode is helpful to eliminate any common mode disturbances in the system. 图 7-2 shows a typical application circuit where the differential output signals SIN_P, SIN_N, COS_P and COS_N are all connected to the four single-ended ADC channels in the external microcontroller. If differential ADC channels are available, then they are recommended. The load capacitors and resistors must match each other to achieve high accuracy. When a fault is detected, the outputs are placed in high-impedance state. TI recommends using pulldown or pullup resistors so that the external microcontroller can detect this case.

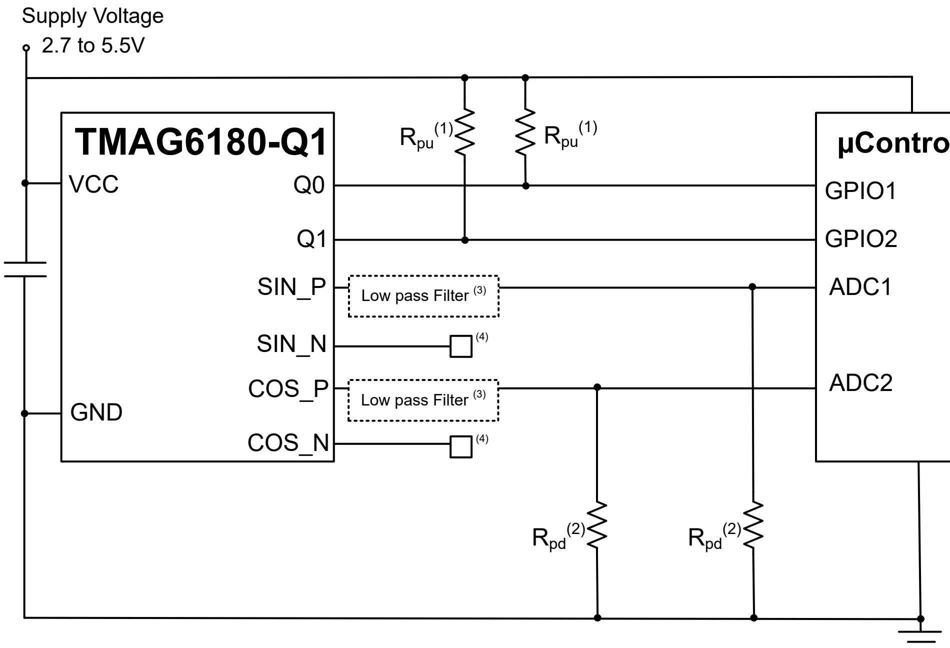
The TMAG6180-Q1 can drive capacitive loads up to 10nF directly on the AMR output pins. The device can also drive up to 100m capacitive loads through a cable with capacitances of 100pF/m. The device can drive resistive loads with the ability to source and sink currents up to 1mA.



(1) 50KΩ < Rpd < 500KΩ (can be left floating if unused)
(2) 5KΩ < Rpu < 1MΩ (can be left floating if unused)
(3) Optional RC filter to reduce noise.
Filter time constant must be lesser than on speed of rotation

图 7-2. Application Diagram for TMAG6180-Q1 in Differential-Ended Output Mode

TI recommends using the single-ended output mode if the number of ADC ports in the microcontroller are limited, or if the number of wires from the sensor to the microcontroller must be kept to a minimum. 图 7-3 shows a typical application circuit where only the positive output channels (SIN_P and COS_P) are connected to single-ended ADCs. The unused output signals (SIN_N and COS_N) can be either left floating or connected to ground through a high resistance. In single-ended output mode, the dynamic range (SNR) and noise immunity is typically reduced compared to the differential output mode. To reduce noise on the outputs and for filtering EMC disturbances, an external low-pass filter such as a first order RC network can be used. The bandwidth of the external filter must be designed based on the rotation speed of the magnetic field to be detected. TI recommends adding pullup or pulldown resistors to ground on the single-ended outputs (SIN_P and COS_P) so the outputs are defined when the outputs are in high-impedance state. The supply voltage of the sensor is used as the reference for the ADCs in the microcontroller.



(1) 50KΩ < Rpd < 500KΩ (can be left floating if unused)
(2) 5KΩ < Rpu < 1MΩ (can be left floating if unused)
(3) Optional RC filter to reduce noise.
Filter time constant must be lesser than on speed of rotation
(4) Can be left floating or connected to ground through R > 100 KΩ

图 7-3. Application Diagram for TMAG6180-Q1 in Single-Ended Output Mode

7.2.1 Design Requirements

图 7-4 shows the center of the magnet aligned with the center of the sensor in a typical on-axis application.

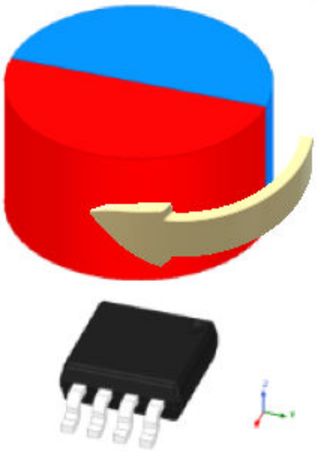


图 7-4. On axis measurement setup for TMAG6180-Q1

Use the parameters listed in 表 7-1 for this design example

表 7-1. Design Parameters

DESIGN PARAMETERS	ON-AXIS MEASUREMENT
V_{CC}	5V
Magnet	Cylinder: 4.7625mm diameter, 12.7mm thick, neodymium N52, Br = 1480
Output mode	Differential-ended
Maximum speed of the motor	8,000 RPM
Desired Angle error across temperature	< 1°
Magnet to sensor placement	End of shaft

7.2.2 Detailed Design Procedure

For accurate angle measurement, the center of the magnet is aligned to the center of the sensor with acceptable tolerances. Follow these steps to calibrate the sensor for best accuracy:

- Reference angle calibration - Set the reference angle based on the magnet alignment to the sensor. This error can be saved in the microcontroller for runtime absolute position calculation. This error is also known as Angle offset in a system.
- Electrical offset calibration - See *Calibration of Sensor Errors* for the offset calibration procedure. If the sensor cannot be rotated across the full range, then the electrical offsets cannot be calibrated.
- Amplitude mismatch calibration - See *Calibration of Sensor Errors* for the amplitude mismatch calibration procedure. If the sensor cannot be rotated across the full range, then the amplitude mismatch cannot be calibrated.
- To extend the angle range from the AMR sensor to 360 degrees, see *Extending the Angle Range to 360 Degrees*

7.2.2.1 Extending the Angle Range to 360 Degrees

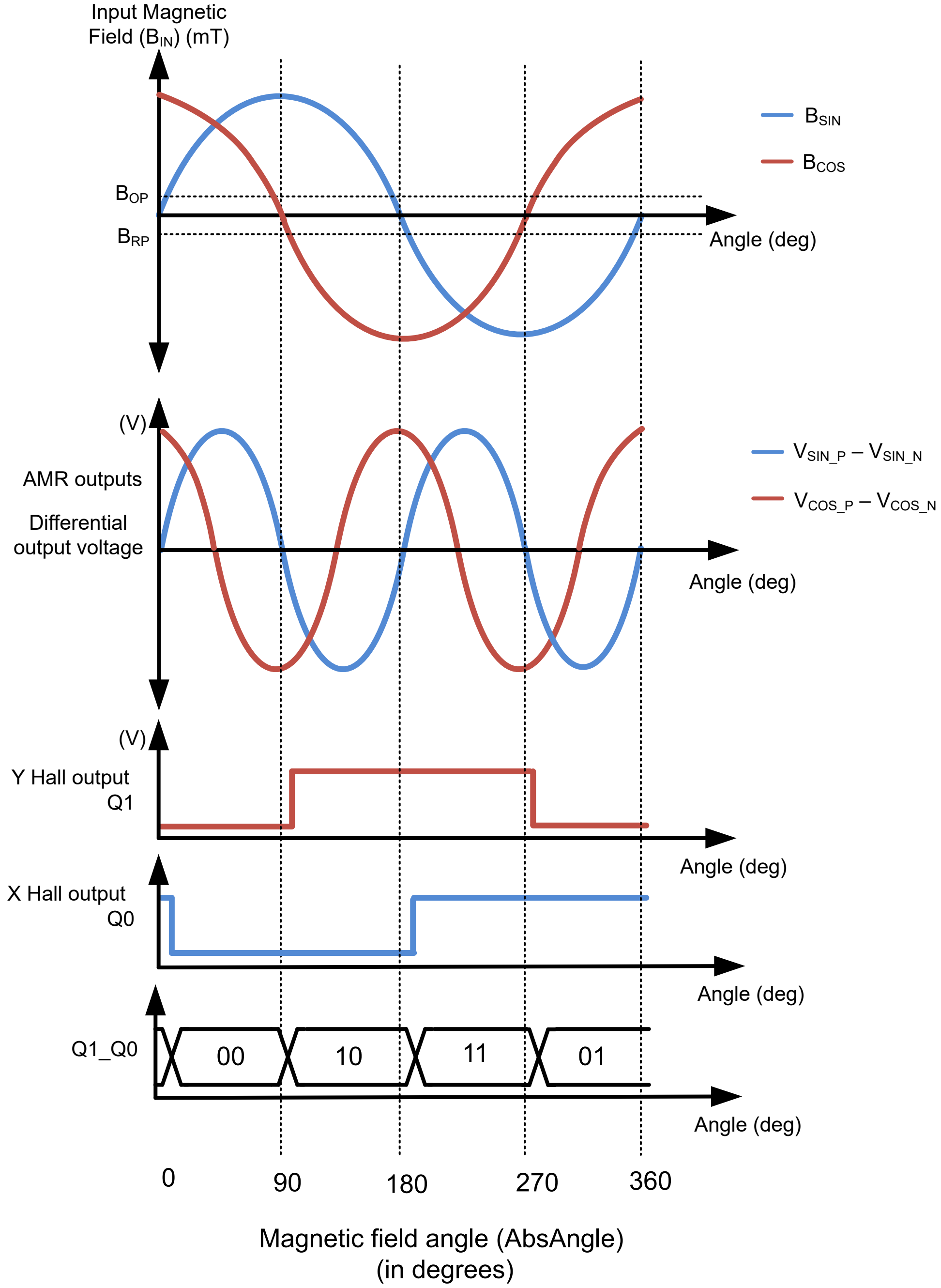


图 7-5. Magnetic Response for a 360° Input Field

图 7-5 shows the response of the differential-ended AMR output signals and the Hall outputs (Q_1, Q_0) for a 360° input magnetic field (B_{IN}).

An example code for extending the angle range from 180 degrees to 360 degrees using the Q0, Q1 outputs is given below ;

```
MeasuredAngle = arctan2(SIN, COS)/2 ; //0-180° angle range , Multiply by 180/Pi if the angle is returned in radians

MeasuredAngle = 90 - MeasuredAngle // If arctan2 function returns from -90deg to 90deg angle range, then use this to convert to 0-180° angle range

if (MeasuredAngle is between 45°-135°) then
(
if (Q1_Q0 is 00b or 10b) then //around 90°
    AbsAngle = MeasuredAngle ;
else //Q1_Q0 is 11b or 01b, around 270°
    AbsAngle = MeasuredAngle + 180°;
)
else //MeasuredAngle is 0°-45° or 135°-180°
(
if (Q1_Q0 is 00b or 01b) then //around 0°
(
if (MeasuredAngle ≥ 135°) then
AbsAngle = MeasuredAngle + 180°;
        else
          //MeasuredAngle is 0-45°
AbsAngle = MeasuredAngle;
)
    else
          //2Digital is 10b or 11b, around 180°
(
if (MeasuredAngle ≥ 135°) then
AbsAngle = MeasuredAngle;
        else
          //MeasuredAngle is 0-45°)
AbsAngle = MeasuredAngle + 180°;
)
)
```

7.2.3 Application Curves

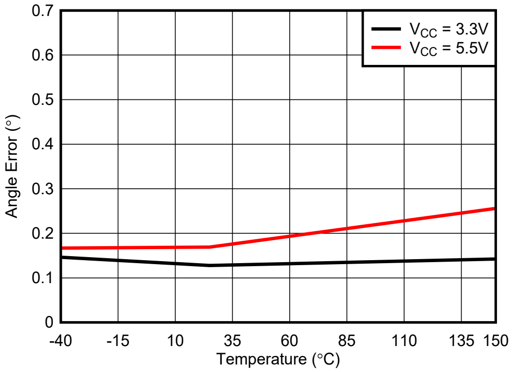


图 7-6. Angle Error with Dynamic Calibration

7.3 Power Supply Recommendations

A decoupling capacitor close to the device must be used to provide local energy with minimal inductance. TI recommends using a ceramic capacitor with a value of at least 0.1µF.

7.4 Layout

7.4.1 Layout Guidelines

Magnetic fields pass through most nonferromagnetic materials with no significant disturbance. Embedding magnetic sensors within plastic or aluminum enclosures and sensing magnets on the outside is common practice. Magnetic fields also easily pass through most printed circuit boards (PCBs), which makes placing the magnet on the opposite side of the PCB possible.

7.4.2 Layout Example

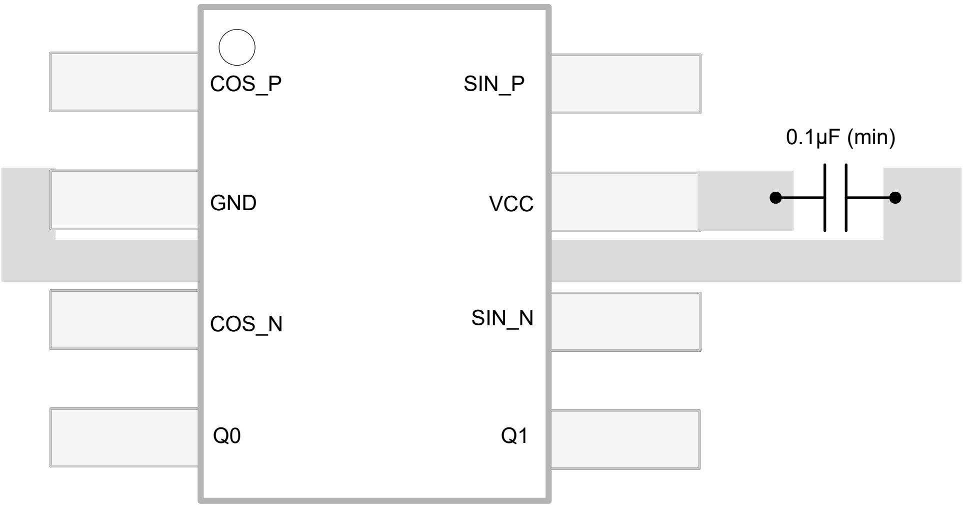


图 7-7. Layout Example With TMAG6180-Q1

8 Device and Documentation Support

8.1 接收文档更新通知

要接收文档更新通知，请导航至 ti.com 上的器件产品文件夹。点击*通知*进行注册，即可每周接收产品信息更改摘要。有关更改的详细信息，请查看任何已修订文档中包含的修订历史记录。

8.2 支持资源

TI E2E™ 中文支持论坛是工程师的重要参考资料，可直接从专家处获得快速、经过验证的解答和设计帮助。搜索现有解答或提出自己的问题，获得所需的快速设计帮助。

链接的内容由各个贡献者“按原样”提供。这些内容并不构成 TI 技术规范，并且不一定反映 TI 的观点；请参阅 TI 的使用条款。

8.3 Trademarks

TI E2E™ is a trademark of Texas Instruments.
所有商标均为其各自所有者的财产。

8.4 静电放电警告

静电放电 (ESD) 会损坏这个集成电路。德州仪器 (TI) 建议通过适当的预防措施处理所有集成电路。如果不遵守正确的处理和安装程序，可能会损坏集成电路。

ESD 的损坏小至导致微小的性能降级，大至整个器件故障。精密的集成电路可能更容易受到损坏，这是因为非常细微的参数更改都可能会导致器件与其发布的规格不相符。

8.5 术语表

TI 术语表	本术语表列出并解释了术语、首字母缩略词和定义。

9 Revision History

Changes from Revision * (March 2023) to Revision A (March 2024)	Page
• 将数据表状态从“预告信息”更改为：“量产数据”	1

10 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
TMAG6180EDGKRQ1	ACTIVE	VSSOP	DGK	8	2500	RoHS & Green	SN	Level-1-260C-UNLIM	-40 to 150	6180	Samples

[1] The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

[2] **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".
RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.
Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

[3] MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

[4] There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

[5] Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

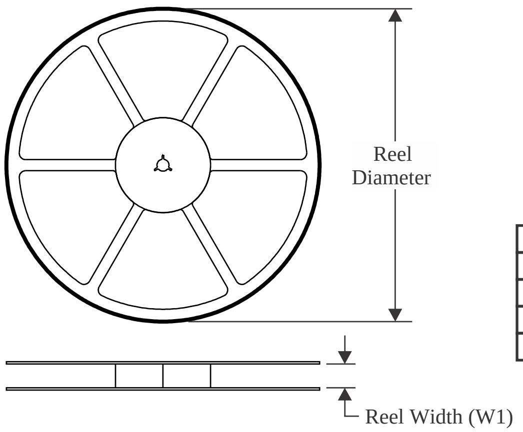
[6] Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

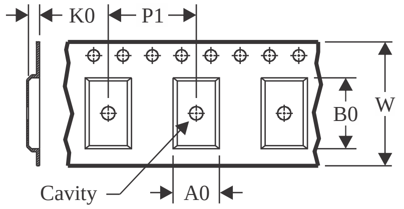
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TAPE AND REEL INFORMATION

REEL DIMENSIONS

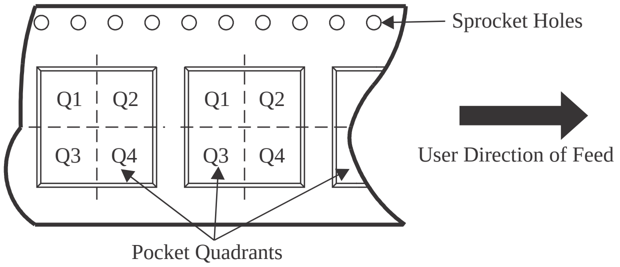


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

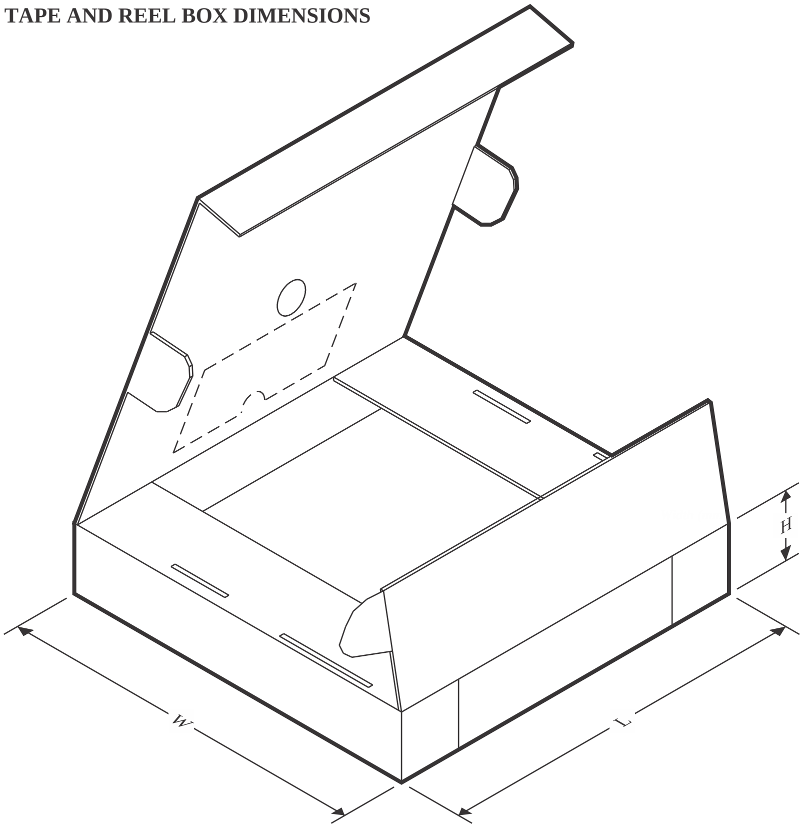
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

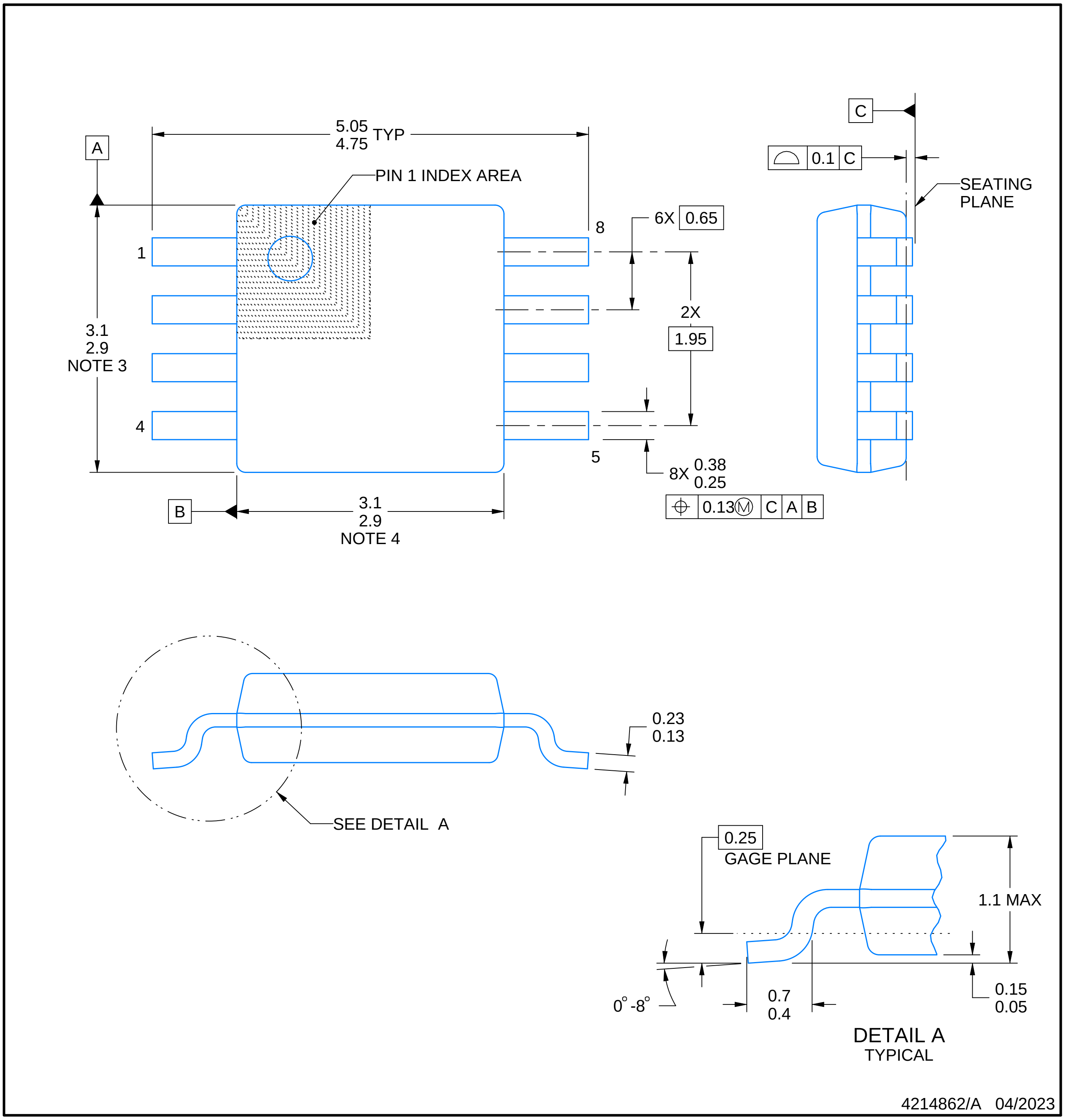
Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TMAG6180EDGKRQ1	VSSOP	DGK	8	2500	330.0	12.4	5.25	3.35	1.25	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TMAG6180EDGKRQ1	VSSOP	DGK	8	2500	366.0	364.0	50.0

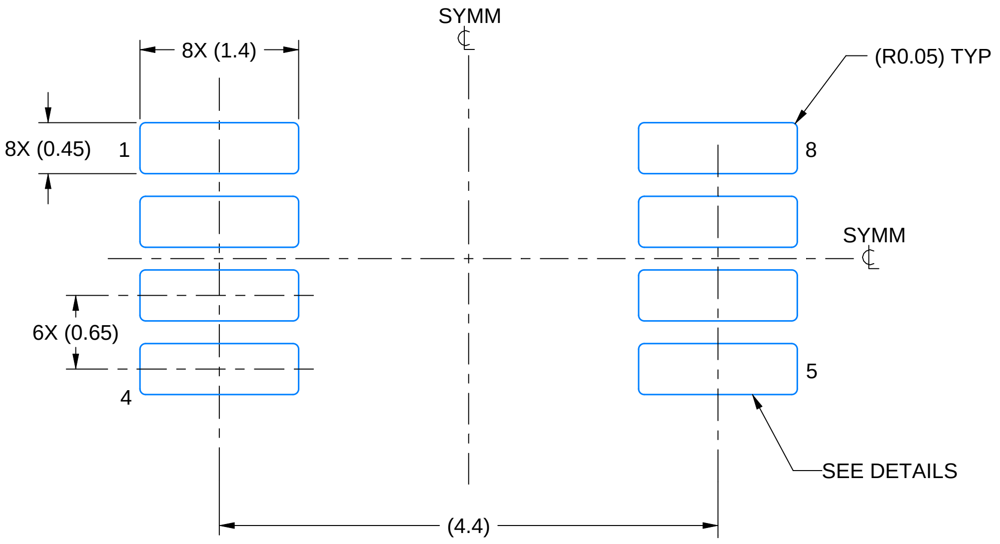


4214862/A 04/2023

PowerPAD is a trademark of Texas Instruments.

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-187.



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 15X

NON-SOLDER MASK
DEFINED
(PREFERRED)

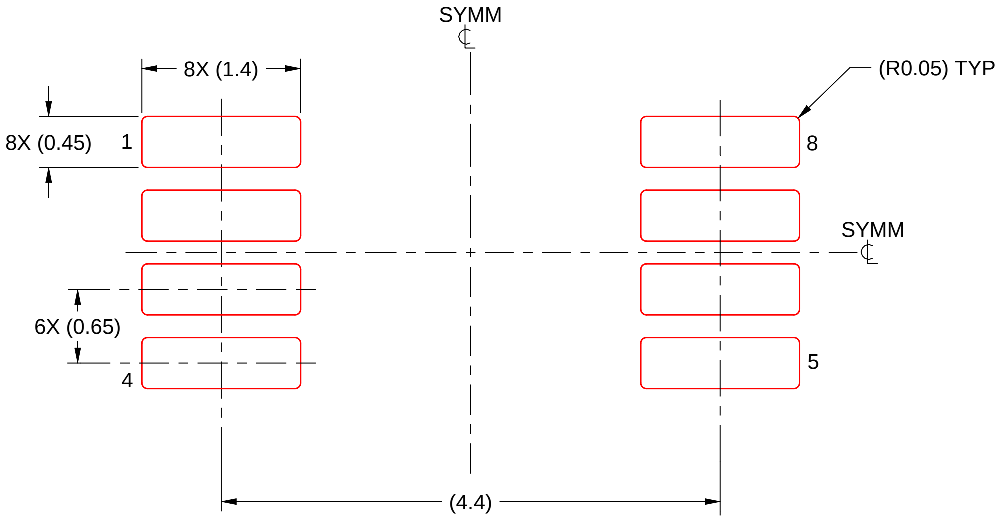
SOLDER MASK
DEFINED

SOLDER MASK DETAILS

4214862/A 04/2023

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.
8. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.
9. Size of metal pad may vary due to creepage requirement.



SOLDER PASTE EXAMPLE
SCALE: 15X

NOTES: (continued)

11. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
12. Board assembly site may have different recommendations for stencil design.

重要声明和免责声明

邮寄地址：Texas Instruments, Post Office Box 655303, Dallas, Texas 75265